



Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-0812-R0

Exhibit 13 Appendix C: T-Coil Data Plot

CELL BC-0

Applicant	Kyocera
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Report #:	CT-S2150-13C-0812-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 08/09/2012

FCC_S2150_TCoil_CELL_Ch.1013 z (axial)

Communication System: CDMA_Tri_BC0&10, Frequency: 824.7 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_1013/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 48.1 dB

ABM1 comp = -4.66 dB A/m

BWC Factor = 0.155041 dB

Location: 1.3, -0.4, 3.7 mm

General Scans_1013/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

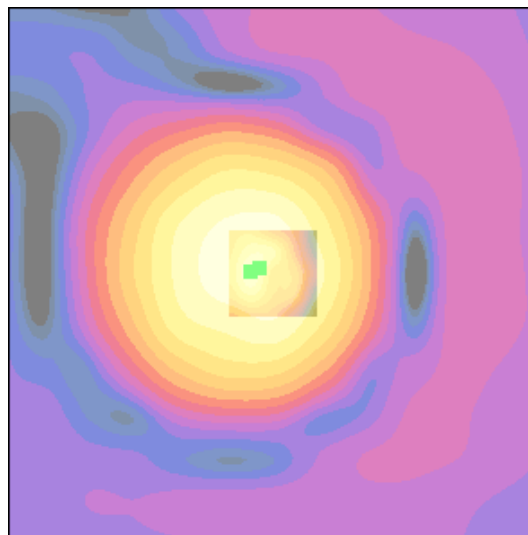
Cursor:

ABM1/ABM2 = 49.0 dB

ABM1 comp = -3.92 dB A/m

BWC Factor = 0.155041 dB

Location: 2, -0.2, 3.7 mm



0 dB = 255.2

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Test Laboratory: COMPTEST/KYOCERA

Date: 08/09/2012

FCC_S2150_TCoil_CELL_Ch. 1013 x (longitudinal)

Communication System: CDMA_Tri_BC0&10, Frequency: 824.7 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_1013/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 44.2 dB

ABM1 comp = -12.5 dB A/m

BWC Factor = 0.155041 dB

Location: -4.6, -3.8, 3.7 mm

General Scans_1013/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

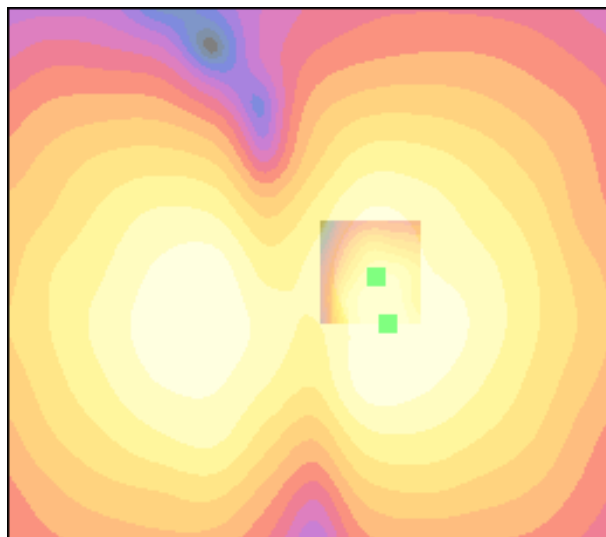
Cursor:

ABM1/ABM2 = 45.6 dB

ABM1 comp = -12.3 dB A/m

BWC Factor = 0.155041 dB

Location: -5.6, -0.2, 3.7 mm



0 dB = 162.7

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Test Laboratory: COMPTEST/KYOCERA

Date: 08/09/2012

FCC_S2150_TCoil_CELL_Ch. 1013 y (transversal)

Communication System: CDMA_Tri_BC0&10, Frequency: 824.7 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_1013/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 44.7 dB

ABM1 comp = -13.1 dB A/m

BWC Factor = 0.155041 dB

Location: 1.3, -7.1, 3.7 mm

General Scans_1013/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

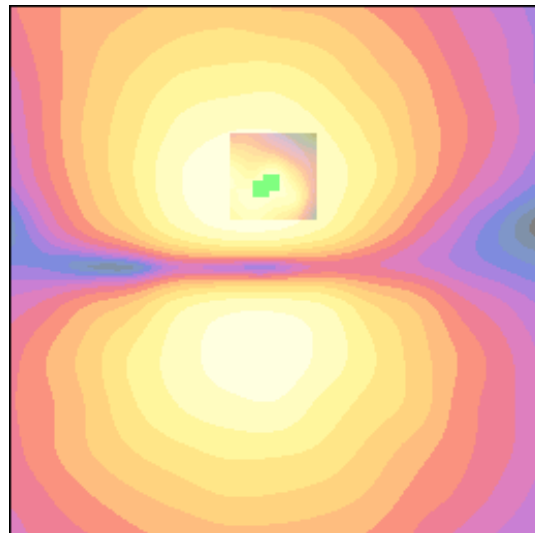
Cursor:

ABM1/ABM2 = 44.7 dB

ABM1 comp = -13.0 dB A/m

BWC Factor = 0.155041 dB

Location: 0.2, -7.7, 3.7 mm



0 dB = 171.7

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Test Laboratory: COMPTEST/KYOCERA

Date: 08/09/2012

FCC_ S2150_TCoil_CELL_Ch.384 z (axial)

Communication System: CDMA_Tri_BC0&10, Frequency: 836.52 MHz, Duty Cycle: 1:1

Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527,Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_384/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 47.3 dB

ABM1 comp = -5.13 dB A/m

BWC Factor = 0.155979 dB

Location: 2.5, 0, 3.7 mm

General Scans_384/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

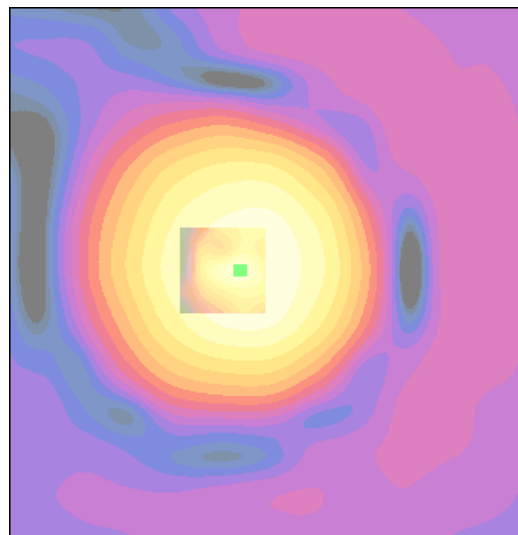
Cursor:

ABM1/ABM2 = 47.5 dB

ABM1 comp = -4.21 dB A/m

BWC Factor = 0.155979 dB

Location: 2.6, 0, 3.7 mm



0 dB = 232.8

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Test Laboratory: COMPTEST/KYOCERA

Date: 08/09/2012

FCC_S2150_TCoil_CELL_Ch.384 x (longitudinal)

Communication System: CDMA_Tri_BC0&10, Frequency: 836.52 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_384/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 45.0 dB

ABM1 comp = -12.2 dB A/m

BWC Factor = 0.155979 dB

Location: -5, -1.7, 3.7 mm

General Scans_384/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

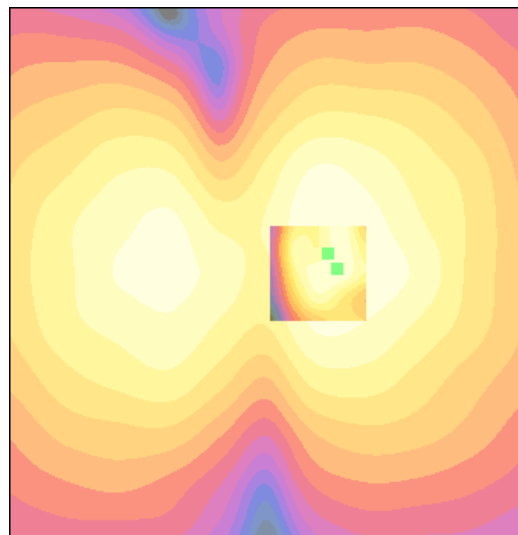
Cursor:

ABM1/ABM2 = 45.2 dB

ABM1 comp = -12.5 dB A/m

BWC Factor = 0.155979 dB

Location: -5.8, -0.4, 3.7 mm



0 dB = 182.1

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Date: 08/09/2012

FCC_S2150_TCoil_CELL_Ch.384 y(transversal)

Communication System: CDMA_Tri_BC0&10, Frequency: 836.52 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_384/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 45.0 dB

ABM1 comp = -12.6 dB A/m

BWC Factor = 0.155979 dB

Location: 3.3, -7.5, 3.7 mm

General Scans_384/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

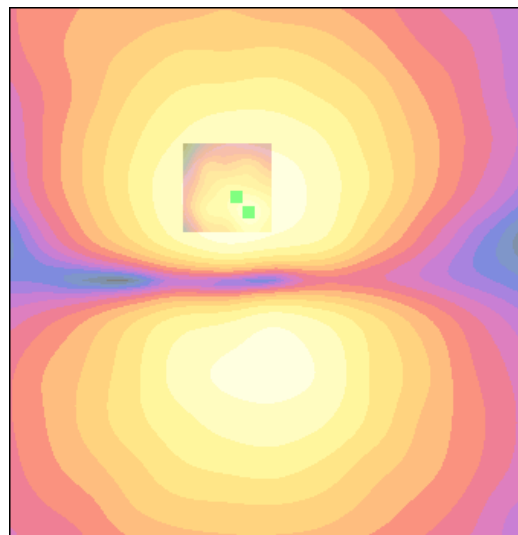
Cursor:

ABM1/ABM2 = 45.1 dB

ABM1 comp = -12.3 dB A/m

BWC Factor = 0.155979 dB

Location: 2.2, -6.1, 3.7 mm



0 dB = 177.3

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Test Laboratory: COMPTEST/KYOCERA

Date: 08/09/2012

FCC_ S2150_TCoil_CELL_Ch. 777 z(axial)

Communication System: CDMA_Tri_BC0&10, Frequency: 848.31 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_777/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 47.5 dB

ABM1 comp = -5.33 dB A/m

BWC Factor = 0.155979 dB

Location: 0.4, 0, 3.7 mm

General Scans_777/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

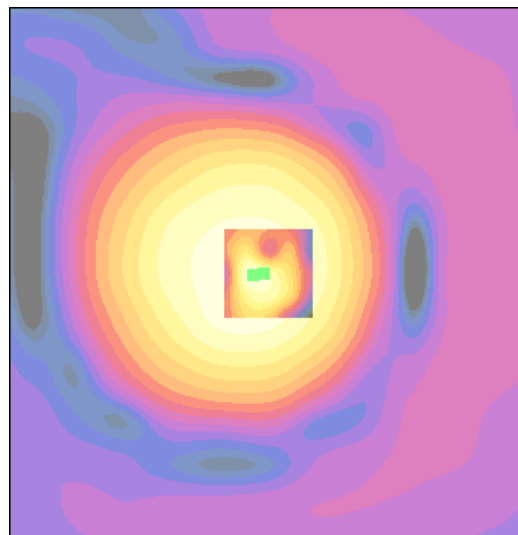
Cursor:

ABM1/ABM2 = 47.4 dB

ABM1 comp = -4.43 dB A/m

BWC Factor = 0.155979 dB

Location: 1.4, 0.2, 3.7 mm



0 dB = 235.8

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Test Laboratory: COMPTEST/KYOCERA

Date: 08/09/2012

FCC_ S2150_TCoil_CELL_Ch. 777 x(longitudinal)

Communication System: CDMA_Tri_BC0&10, Frequency: 848.31 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_777/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 45.7 dB

ABM1 comp = -12.1 dB A/m

BWC Factor = 0.155979 dB

Location: -5, -0.4, 3.7 mm

General Scans_777/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

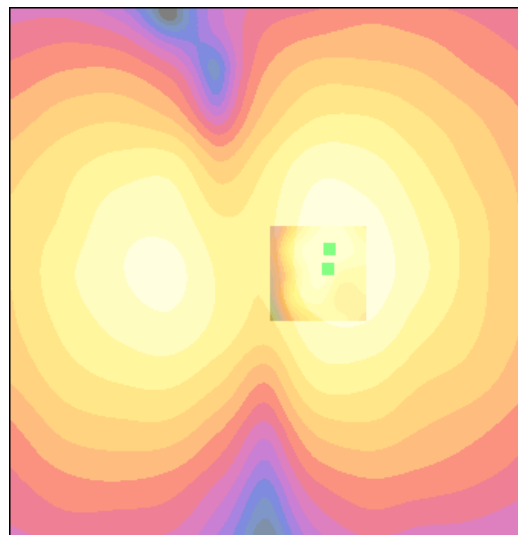
Cursor:

ABM1/ABM2 = 45.1 dB

ABM1 comp = -12.3 dB A/m

BWC Factor = 0.155979 dB

Location: -5.2, -2, 3.7 mm



0 dB = 179.9

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Test Laboratory: COMPTEST/KYOCERA

Date: 08/09/2012

FCC_ S2150_TCoil_CELL_Ch. 777 y(transveral)

Communication System: CDMA_Tri_BC0&10, Frequency: 848.31 MHz, Duty Cycle: 1:1

Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527,Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_777/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

ABM1/ABM2 = 43.8 dB

ABM1 comp = -13.8 dB A/m

BWC Factor = 0.155979 dB

Location: 1.3, -5.4, 3.7 mm

General Scans_777/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

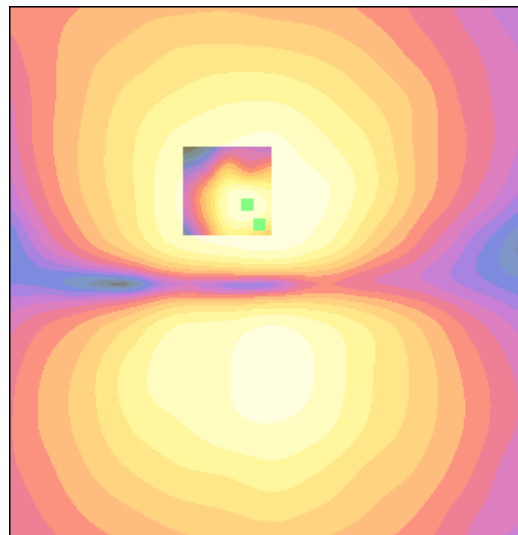
Cursor:

ABM1/ABM2 = 45.1 dB

ABM1 comp = -12.4 dB A/m

BWC Factor = 0.155979 dB

Location: 2.4, -7.1, 3.7 mm



0 dB = 155.4

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FCC ID:	V65S2150
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AWS

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-0812-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 08/24/2012

FCC_ S2150_TCoil_AWS Ch. 25 z(axial)

Communication System: AWS-1700, Frequency: 1711.25 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_25/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 48.7 dB

ABM1 comp = -4.58 dB A/m

BWC Factor = 0.155041 dB

Location: 0, 0, 3.7 mm

General Scans_25/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

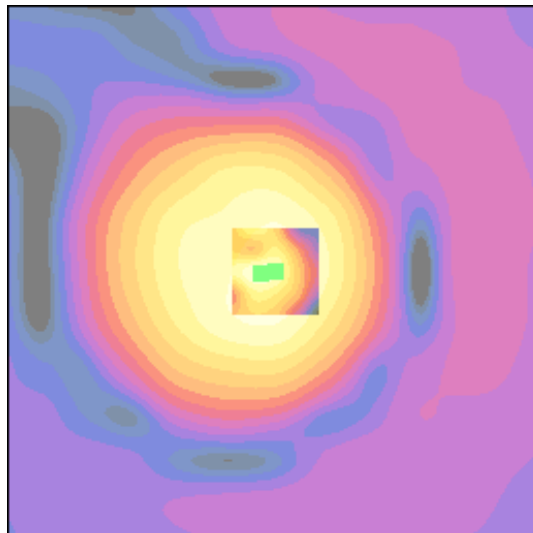
Cursor:

ABM1/ABM2 = 48.5 dB

ABM1 comp = -4.31 dB A/m

BWC Factor = 0.155041 dB

Location: 1.4, 0.2, 3.7 mm



0 dB = 272.7

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Test Laboratory: COMPTEST/KYOCERA

Date: 08/24/2012

FCC_S2150_TCoil_AWS_Ch. 25 x(longitudinal)

Communication System: AWS-1700, Frequency: 1711.25 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_25/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 44.0 dB

ABM1 comp = -14.0 dB A/m

BWC Factor = 0.155041 dB

Location: -5.8, 2.9, 3.7 mm

General Scans_25/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

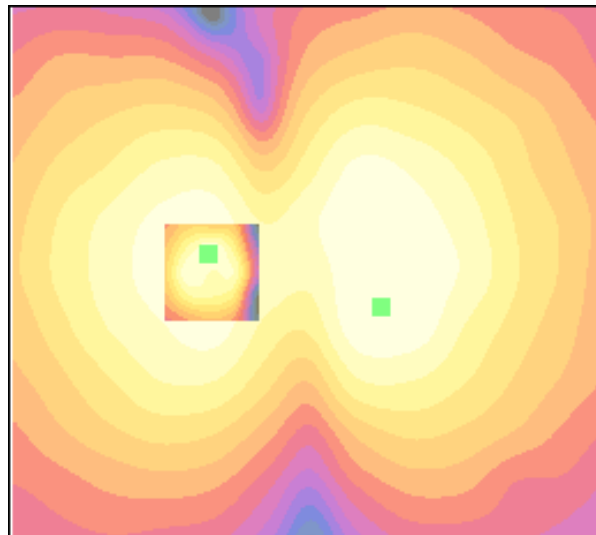
Cursor:

ABM1/ABM2 = 44.6 dB

ABM1 comp = -13.9 dB A/m

BWC Factor = 0.155041 dB

Location: 8.5, -1.6, 3.7 mm



0 dB = 158.3

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-0812-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 08/24/2012

FCC_S2150_TCoil_AWS_Ch. 25 y(transveral)

Communication System: AWS-1700, Frequency: 1711.25 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_25/y (transveral) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 44.7 dB

ABM1 comp = -12.5 dB A/m

BWC Factor = 0.155041 dB

Location: 0.4, -7.5, 3.7 mm

General Scans_25/y (transveral) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

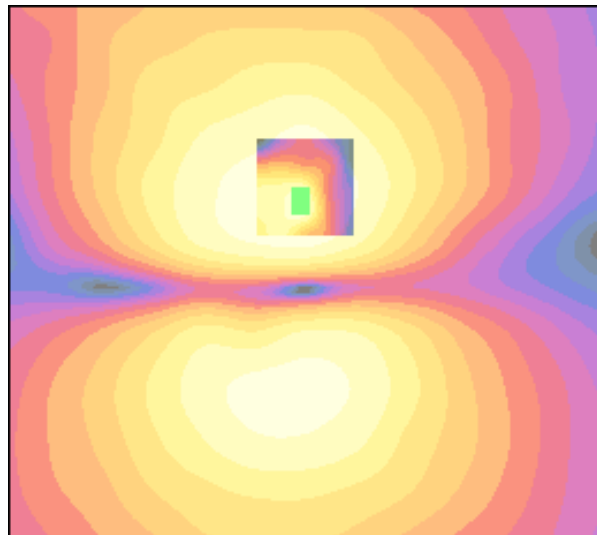
Cursor:

ABM1/ABM2 = 44.7 dB

ABM1 comp = -12.6 dB A/m

BWC Factor = 0.155041 dB

Location: 0.4, -6.7, 3.7 mm



0 dB = 171.1

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-0812-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 08/24/2012

FCC_ S2150_TCoil_AWS Ch. 450 z(axial)

Communication System: AWS-1700, Frequency: 1732.5 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_ 450/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 47.0 dB

ABM1 comp = -5.52 dB A/m

BWC Factor = 0.155041 dB

Location: 2.1, 0.8, 3.7 mm

General Scans_ 450/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

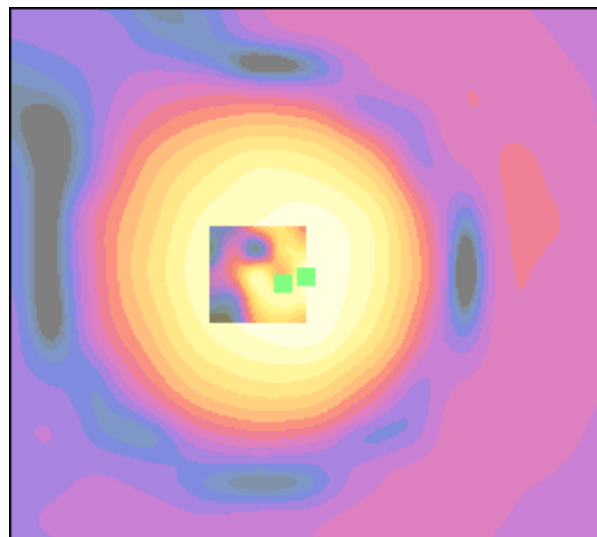
Cursor:

ABM1/ABM2 = 48.0 dB

ABM1 comp = -5.29 dB A/m

BWC Factor = 0.155041 dB

Location: 0.2, 0.2, 3.7 mm



0 dB = 224.9

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-0812-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 08/24/2012

FCC_S2150_TCoil_AWS_Ch. 450 x(longitudinal)

Communication System: AWS-1700, Frequency: 1732.5 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_450/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 44.4 dB

ABM1 comp = -13.3 dB A/m

BWC Factor = 0.155041 dB

Location: -7.5, -0.8, 3.7 mm

General Scans_450/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

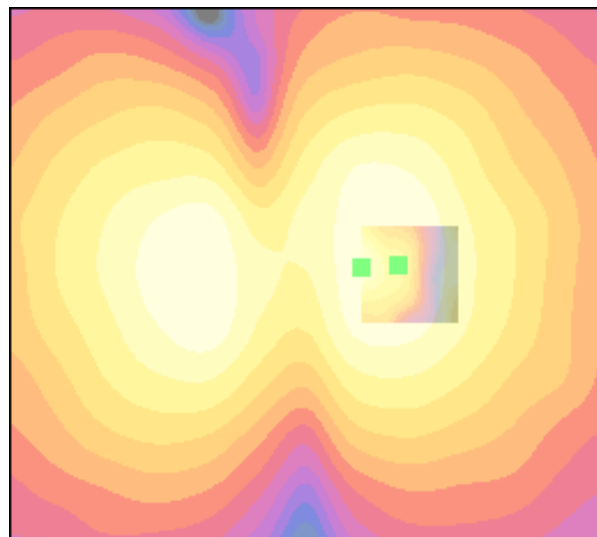
Cursor:

ABM1/ABM2 = 45.5 dB

ABM1 comp = -12.1 dB A/m

BWC Factor = 0.155041 dB

Location: -4.3, -0.6, 3.7 mm



0 dB = 189.3

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-0812-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 08/24/2012

FCC_ S2150_TCoil_AWS_Ch. 450 y(transveral)

Communication System: AWS-1700, Frequency: 1732.5 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_450/y (transveral) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 44.2 dB

ABM1 comp = -13.2 dB A/m

BWC Factor = 0.155041 dB

Location: 0, -6.3, 3.7 mm

General Scans_450/y (transveral) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

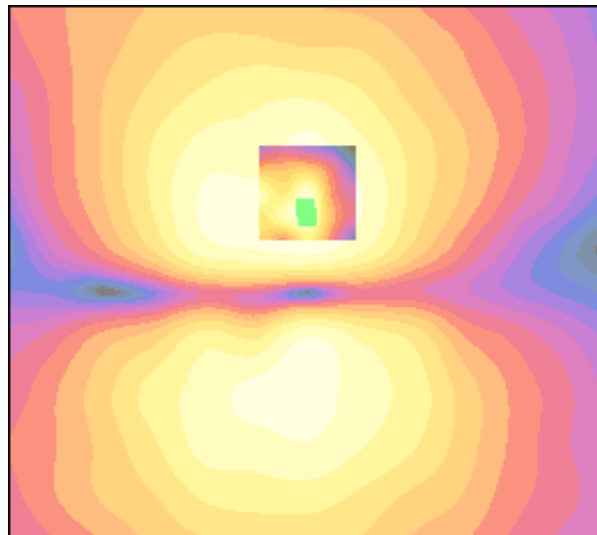
Cursor:

ABM1/ABM2 = 45.1 dB

ABM1 comp = -12.7 dB A/m

BWC Factor = 0.155041 dB

Location: 0.2, -7.1, 3.7 mm



0 dB = 162.3

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-0812-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 08/24/2012

FCC_ S2150_TCoil_AWS Ch. 875 z(axial)

Communication System: AWS-1700, Frequency: 1753.75 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_ 875/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 48.5 dB

ABM1 comp = -4.90 dB A/m

BWC Factor = 0.155041 dB

Location: 0.8, 0, 3.7 mm

General Scans_ 875/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

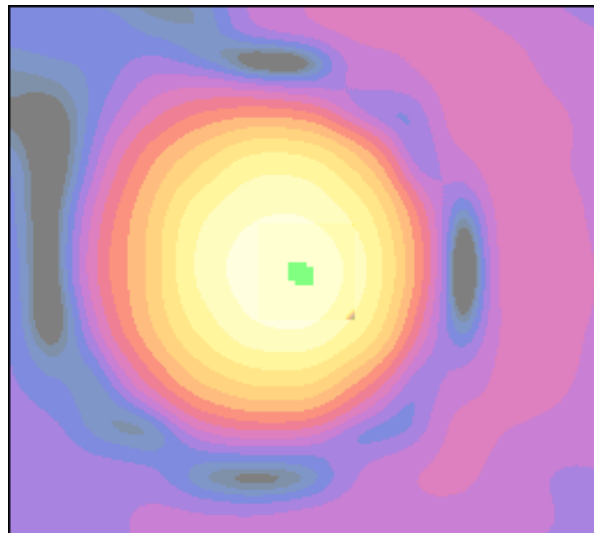
Cursor:

ABM1/ABM2 = 48.3 dB

ABM1 comp = -5.31 dB A/m

BWC Factor = 0.155041 dB

Location: 0.2, 0.4, 3.7 mm



0 dB = 266.0

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-0812-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 08/24/2012

FCC_S2150_TCoil_AWS_Ch. 875 x(longitudinal)

Communication System: AWS-1700, Frequency: 1753.75 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_875/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 44.7 dB

ABM1 comp = -12.6 dB A/m

BWC Factor = 0.155041 dB

Location: -5.8, -0.4, 3.7 mm

General Scans_875/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

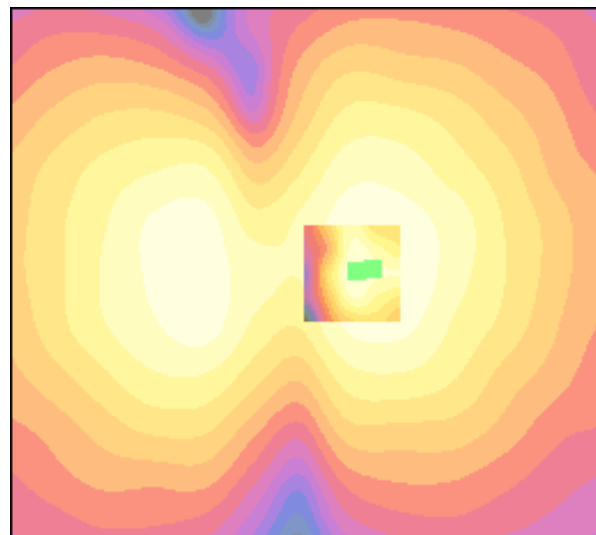
Cursor:

ABM1/ABM2 = 45.4 dB

ABM1 comp = -12.2 dB A/m

BWC Factor = 0.155041 dB

Location: -4.6, -0.2, 3.7 mm



0 dB = 170.9

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-0812-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 08/24/2012

FCC_S2150_TCoil_AWS_Ch. 875 y(transveral)

Communication System: AWS-1700, Frequency: 1753.75 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_875/y (transveral) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 44.5 dB

ABM1 comp = -13.3 dB A/m

BWC Factor = 0.155041 dB

Location: 0, -5.8, 3.7 mm

General Scans_875/y (transveral) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

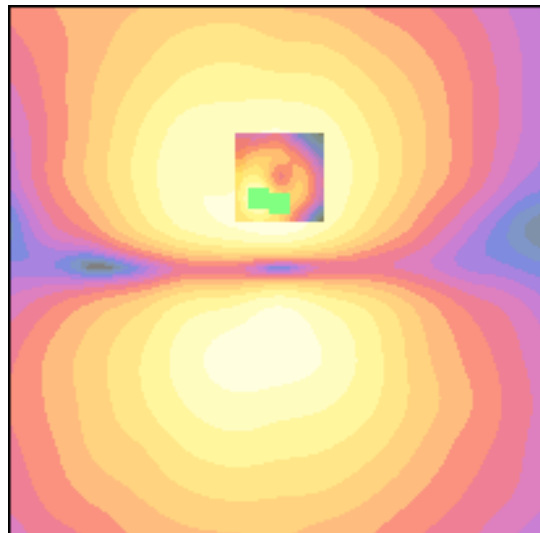
Cursor:

ABM1/ABM2 = 45.5 dB

ABM1 comp = -12.1 dB A/m

BWC Factor = 0.155041 dB

Location: 2, -6.3, 3.7 mm



0 dB = 168.5

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-0812-R0

PCS

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-0812-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 08/10/2012

FCC_ S2150_TCoil_PCS_Ch. 25 z(axial)

Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_25/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 47.7 dB

ABM1 comp = -4.91 dB A/m

BWC Factor = 0.155041 dB

Location: 1.7, -0.4, 3.7 mm

General Scans_25/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

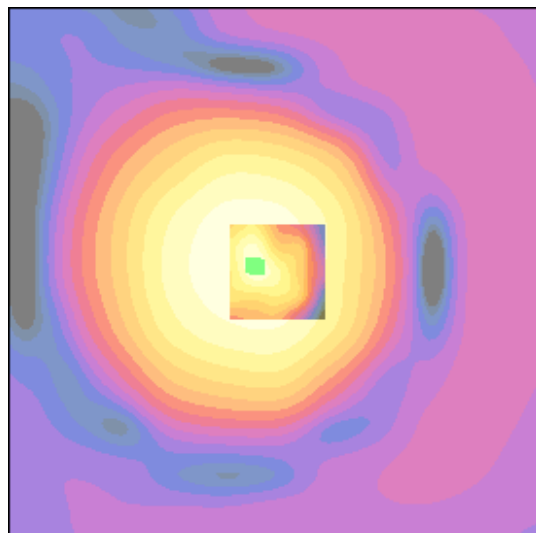
Cursor:

ABM1/ABM2 = 48.5 dB

ABM1 comp = -4.16 dB A/m

BWC Factor = 0.155041 dB

Location: 2, -0.6, 3.7 mm



0 dB = 243.7



Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-0812-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 08/10/2012

FCC_S2150_TCoil_PCS_Ch. 25 x(longitudinal)

Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1

Medium: T-Coil,Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC,Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527,Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_25/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 45.7 dB

ABM1 comp = -11.9 dB A/m

BWC Factor = 0.155041 dB

Location: -5.4, -1.3, 3.7 mm

General Scans_25/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

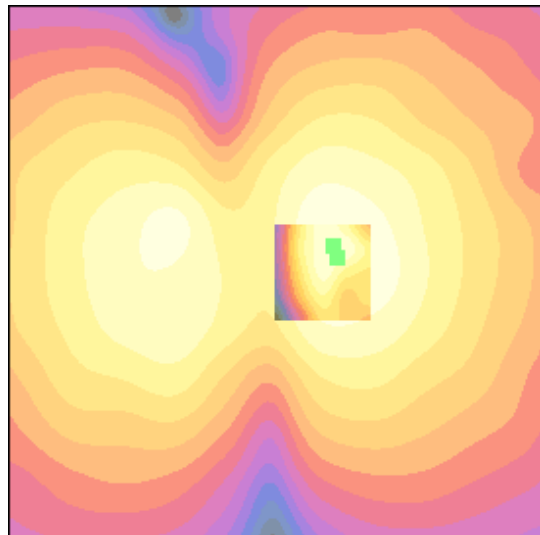
Cursor:

ABM1/ABM2 = 45.5 dB

ABM1 comp = -12.3 dB A/m

BWC Factor = 0.155041 dB

Location: -5.2, -2.2, 3.7 mm



0 dB = 193.4

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-0812-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 08/10/2012

FCC_ S2150_TCoil_PCS_ Ch. 25 y(transversal)

Communication System: CDMA-1900, Frequency: 1851.25 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_25/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 44.2 dB

ABM1 comp = -13.2 dB A/m

BWC Factor = 0.155041 dB

Location: 0.8, -6.3, 3.7 mm

General Scans_25/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155041 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

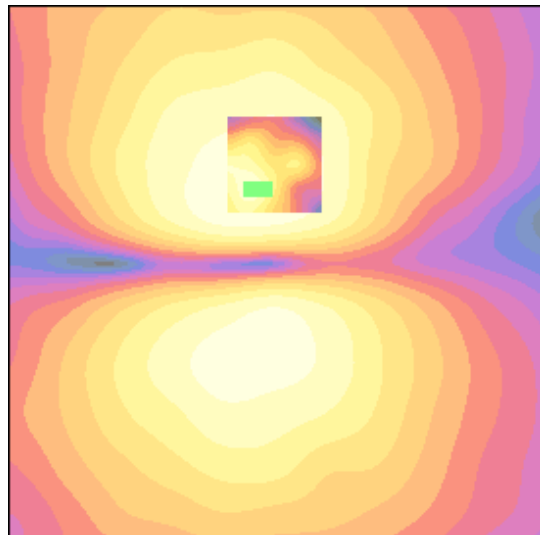
Cursor:

ABM1/ABM2 = 44.5 dB

ABM1 comp = -13.0 dB A/m

BWC Factor = 0.155041 dB

Location: 2, -6.3, 3.7 mm



0 dB = 161.7

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-0812-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 08/10/2012

FCC_ S2150_TCoil_PCS Ch. 600 z(axial)

Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_ 600/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 48.2 dB

ABM1 comp = -4.78 dB A/m

BWC Factor = 0.155979 dB

Location: 2.5, -0.8, 3.7 mm

General Scans_ 600/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

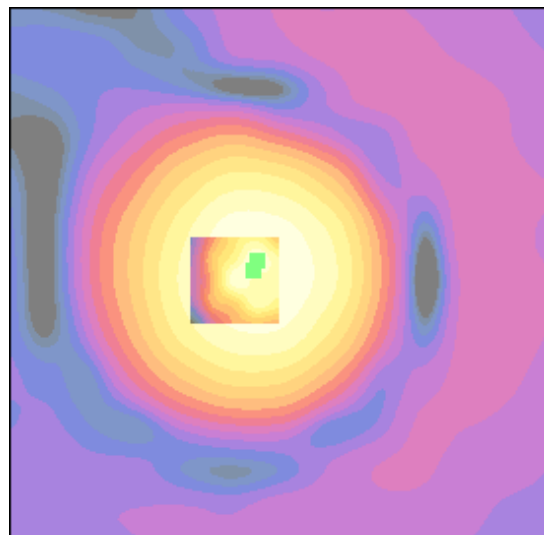
Cursor:

ABM1/ABM2 = 48.1 dB

ABM1 comp = -4.72 dB A/m

BWC Factor = 0.155979 dB

Location: 2.2, -1.8, 3.7 mm



0 dB = 258.4

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-0812-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 08/10/2012

FCC_ S2150_TCoil_PCS Ch. 600 x (longitudinal)

Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_600/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 44.5 dB

ABM1 comp = -13.1 dB A/m

BWC Factor = 0.155979 dB

Location: -5.8, -0.8, 3.7 mm

General Scans_600/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

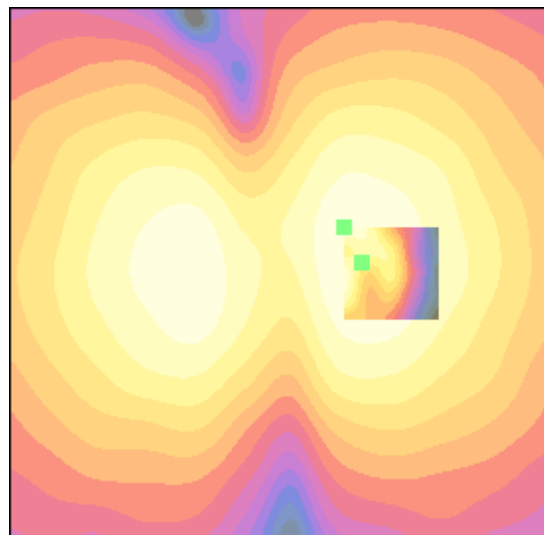
Cursor:

ABM1/ABM2 = 45.2 dB

ABM1 comp = -12.7 dB A/m

BWC Factor = 0.155979 dB

Location: -4.3, -4, 3.7 mm



0 dB = 167.0

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-0812-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 08/10/2012

FCC_S2150_TCoil_PCS_Ch. 600 y(transversal)

Communication System: CDMA-1900, Frequency: 1880 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_600/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 44.7 dB

ABM1 comp = -13.1 dB A/m

BWC Factor = 0.155979 dB

Location: 1.3, -6.3, 3.7 mm

General Scans_600/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

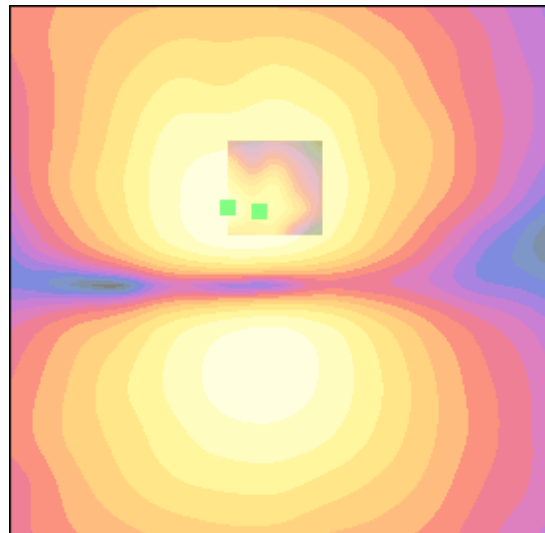
Cursor:

ABM1/ABM2 = 45.3 dB

ABM1 comp = -12.6 dB A/m

BWC Factor = 0.155979 dB

Location: 4, -6.5, 3.7 mm



0 dB = 171.7

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-0812-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 08/10/2012

FCC_S2150_TCoil_PCS_Ch.1175 z(axial)

Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_1175/z (axial) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 47.7 dB

ABM1 comp = -4.93 dB A/m

BWC Factor = 0.155979 dB

Location: 1.7, -0.4, 3.7 mm

General Scans_1175/z (axial) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

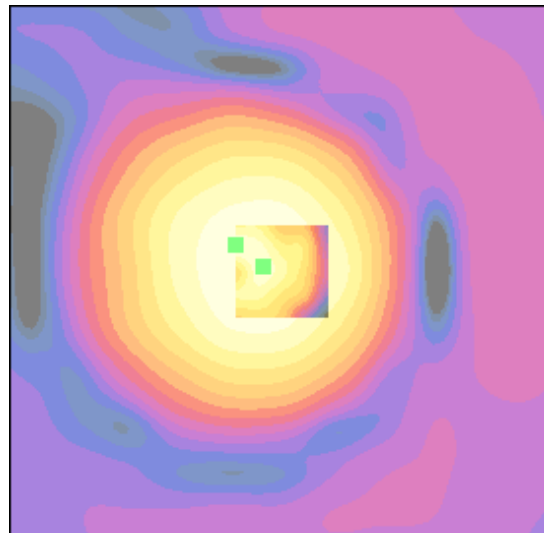
Cursor:

ABM1/ABM2 = 47.8 dB

ABM1 comp = -5.55 dB A/m

BWC Factor = 0.155979 dB

Location: 4, -2.2, 3.7 mm



0 dB = 241.6

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-0812-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 08/10/2012

FCC_S2150_TCoil_PCS_Ch. 1175 x(longitudinal)

Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_1175/x (longitudinal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 45.0 dB

ABM1 comp = -12.8 dB A/m

BWC Factor = 0.155979 dB

Location: -5.4, -0.4, 3.7 mm

General Scans_1175/x (longitudinal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

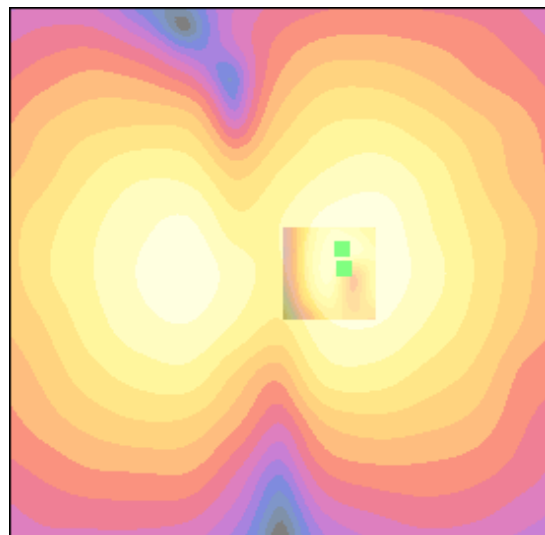
Cursor:

ABM1/ABM2 = 45.2 dB

ABM1 comp = -12.4 dB A/m

BWC Factor = 0.155979 dB

Location: -5.4, -2.2, 3.7 mm



0 dB = 182.1

Applicant	Kyocera
FCC ID:	V65S2150
Report #:	CT-S2150-13C-0812-R0

Test Laboratory: COMPTEST/KYOCERA

Date: 08/10/2012

FCC_ S2150_TCoil_PCS_ Ch. 1175 y(transversal)

Communication System: CDMA-1900, Frequency: 1908.75 MHz, Duty Cycle: 1:1

Medium: T-Coil, Medium parameters used: $\sigma = 0$ mho/m, $\epsilon_r = 1$; $\rho = 0$ kg/m³

Phantom: HAC Test Arch with AMCC, Phantom section: TCoil Section

DASY4 Configuration:

Probe: AM1DV2 - 1045, , Calibrated: 9/15/2011

Sensor-Surface: 0mm (Fix Surface),

Electronics: DAE4 Sn527, Calibrated: 7/30/2012

Measurement SW: DASY4, V4.7 Build 80

Postprocessing SW: SEMCAD, V1.8 Build 186

Temperature:

Room T = 21.8 +/- 1 deg C, Liquid T = 22.0 +/- 1 deg C

General Scans_ 1175/y (transversal) 4.2mm 50 x 50/ABM Interpolated SNR(x,y,z) (121x121x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

Cursor:

ABM1/ABM2 = 44.3 dB

ABM1 comp = -13.4 dB A/m

BWC Factor = 0.155979 dB

Location: 0.4, -6.3, 3.7 mm

General Scans_ 1175/y (transversal) fine 2mm 8 x 8/ABM Interpolated SNR(x,y,z) (41x41x1):

Measurement grid: dx=10mm, dy=10mm

Signal Type: Audio File (.wav) 48k_voice_1kHz_1s.wav

BWC applied: 0.155979 dB

Device Reference Point: 0.000, 0.000, -6.30 mm

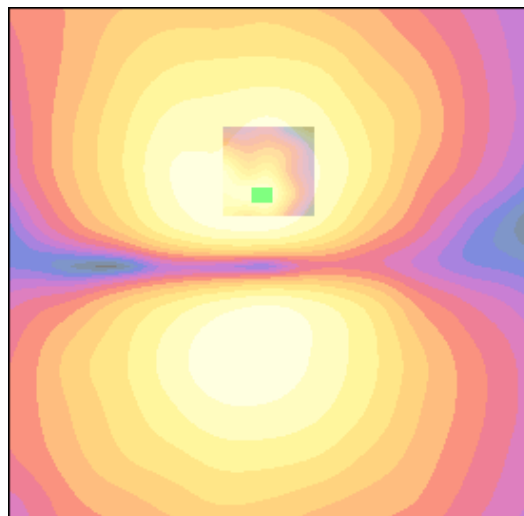
Cursor:

ABM1/ABM2 = 45.2 dB

ABM1 comp = -12.5 dB A/m

BWC Factor = 0.155979 dB

Location: 0.8, -6.3, 3.7 mm



0 dB = 163.2